

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TIANMING ZHANG	01/30/2023
JASON YE	01/28/2023
SHANGYU LI	01/28/2023
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	18162069
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ASSIGNMENT

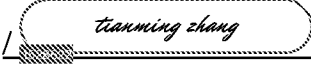
WHEREAS, **TIANMING ZHANG**, a citizen of the United States of America, residing at 22 Woodstock Avenue, Brighton, Massachusetts 02135, **JASON YE**, a citizen of the People's Republic of China, residing at Jin Xi Yuan, Room 503, Building 13, Suzhou Industrial Park, Suzhou City, Jiangsu Province and **SHANGYU LI**, a citizen of the People's Republic of China, residing at Twelve Villages of Tianlin, Xuhui District, Shanghai, China, hereinafter called the "Assignors", have made the invention described in the United States patent application entitled **DYNAMIC NODE CLUSTER WITH STORAGE ARRAY**, Attorney Docket No. 102450.01088 (131428.01), for a full description of which reference is here made to an application for Letters Patent of the United States filed on January 31, 2023 and assigned Application Serial No. 18/162069; and

For good and valuable consideration, the receipt of which is hereby acknowledged, we hereby also sell, assign and transfer unto **DELL PRODUCTS L.P.**, the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in the United States of America and all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and we further authorize **DELL PRODUCTS L.P.** to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation, continuation-in-part, or reissue, to **DELL PRODUCTS L.P.**, for the sole use and benefit of **DELL PRODUCTS L.P.**, its successors, assigns and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to **DELL PRODUCTS L.P.**

We agree that, when requested, we will, without charge to **DELL PRODUCTS L.P.**, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in **DELL PRODUCTS L.P.**, its successors, assigns and legal representatives or nominees.

We covenant with DELL PRODUCTS L.P., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

NAME OF FIRST INVENTOR	TIANMING ZHANG
SIGNATURE OF FIRST INVENTOR	 /
DATE	January 30, 2023

NAME OF SECOND INVENTOR	JASON YE
SIGNATURE OF SECOND INVENTOR	<u>Jason Ye</u>
DATE	<u>1.28.2003</u>

NAME OF THIRD INVENTOR	SHANGYU LI
SIGNATURE OF THIRD INVENTOR	/ <u>Shangyu Li</u> /
DATE	<u>01/28/2023</u>